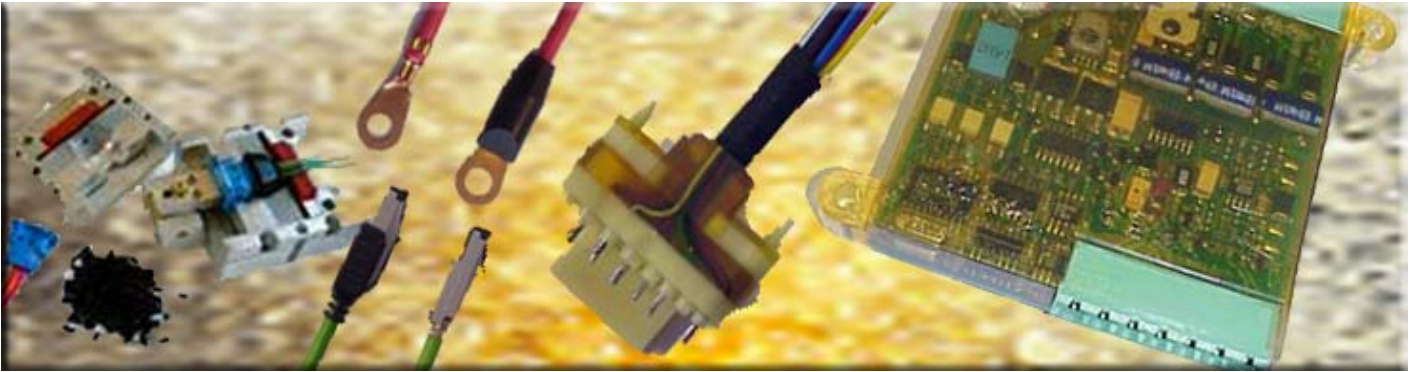


POWERBOND APPLICATION LEAFLET



AN INTRODUCTION TO USING POLYAMIDE ADHESIVES FOR ELECTRICAL & ELECTRONIC POTTING, ENCAPSULATION & LOW PRESSURE MOULDING

POTTING & ENCAPSULATION



A stereo jack incorporating Bluetooth technology was waterproofed using polyamide hot melt saving substantial costs.

Traditional Epoxy and Silicone compounds used for potting and encapsulation are time consuming, costly, difficult to handle and inefficient.

There is now a better alternative. Powerbond produce a range of specialist Polyamide Hotmelt Adhesives in both stick and granulated formats to suit even the most demanding of applications. The adhesive program is supported by a NEW range of innovative application systems to enable our customers to increase production whilst driving down costs.

Applications for these materials and processes are growing rapidly, especially in the fields of electronic control & regulation, data communication & processing, automotive and household appliances.

ADVANTAGES OF POLYAMIDE HOTMELT- vs- TWO PART COMPOUNDS

- **FAST SETTING TIMES OF BETWEEN 5 SEC'S AND 2 MINUTES.**
- **NO NEED FOR DRYING RACKS, FIXTURES OR JIGS**
- **NO NEED FOR OVENS OR VACUUM CHAMBERS**
- **NO MIXING AND NO WASTE**
- **NO CLEANING OR FLUSHING REQUIRED**
- **CLEAN AND FAST APPLICATION**
- **PROTECT COMPONENTS TO IP675**
- **HIGH BOND STRENGTH FOR PERFECT WATER TIGHT SEALS**
- **NO MESSY RESIDUE**
- **VO AND V2 FIRE RETARDANT**
- **LOW VISCOSITY, GOOD FLOW CHARACTERISTICS**
- **SUPERIOR CHEMICAL RESISTANCE**
- **HIGH TEMPERATURE RESISTANCE -55c +150c**
- **ENCAPSULATION TO PCB WITHOUT DAMAGING COMPONENTS**
- **FLEXIBLE STABILISATION OF COMPONENTS**
- **EXCELLENT ELECTRICAL PROPERTIES**
- **UL94 AND ON REQUEST UL746A**
- **CONSISTENT CURE QUALITY**
- **NO CONSUMABLES**

APPLICATION EQUIPMENT Grow at your own pace. Whether your interest is development, small output, multiple operators or main line production, our range includes everything from hand held and hands free bench mounted, variable temperature controlled 12mm stick and total melt guns, through to fully computerised ZXY robots and dedicated low pressure moulding systems.



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LOW PRESSURE MOULDING APPLICATIONS

Humidity & Mechanical Load Protection

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◀ **Low Pressure over moulding of a large PC Board** with mounted connectors. It was encapsulated in one operation. Single cavity mould with mould cooling system, core punch and ejectors.



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Low Pressure over moulding of a 3 Terminal Connector ▶
Twin cavity mould with mould cooling system



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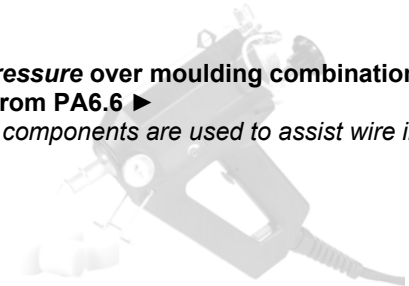
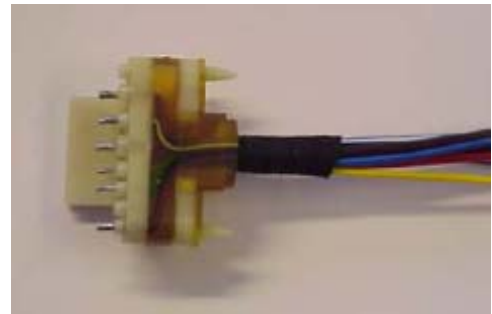


◀ **Low Pressure over moulding of a Fabric Hose (Braided hose)**
Attachment onto a cable. A twin cavity mould with mould cooling system for moulding two components in one operation.



Low Pressure over moulding combination with plastic parts
made from PA6.6 ▶
(PA6.6 components are used to assist wire insertion)

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POWERBOND

LOW PRESSURE MOULDING APPLICATIONS

Humidity & Mechanical Load Protection

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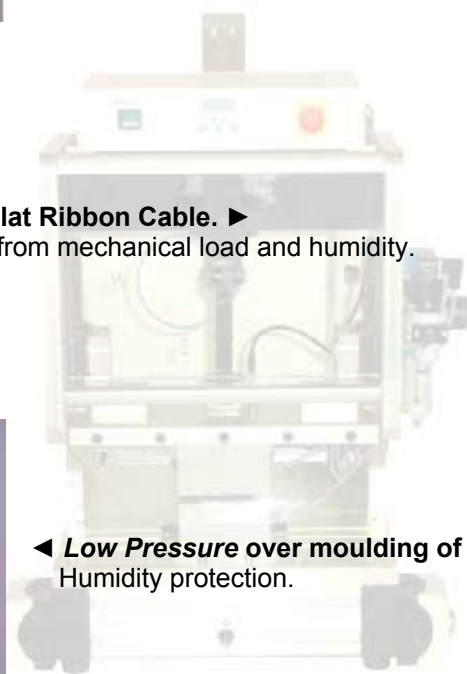
◀ **Low Pressure** over moulding of a Ring Tongue.



Low Pressure over moulding of a Flat Ribbon Cable. ▶

For connections that need protecting from mechanical load and humidity.

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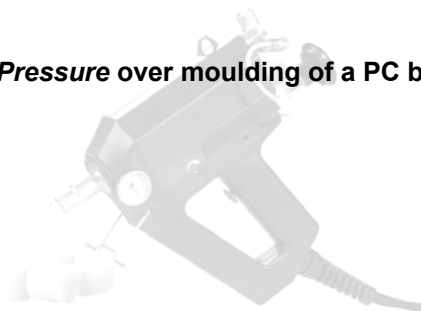


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◀ **Low Pressure** over moulding of a Power Plug.
Humidity protection.

Low Pressure over moulding of a PC board with Keys and LED's. ▶



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For more information or technical assistance please contact: Powerbond Adhesives Ltd. Tel: 01782 823874
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